IPC ASSOCIATION ELECTRONIC	Material Compo © Copyright 2005. II international and Pan	PC, Bannockb	urn, Illinois. A	all rights reserved u	inder both	This docume level parts, t	ent is a declar he declaration	ation of t	the substances basses all lowe	within the r level ma	e manufactur terials for w	er listed ite hich the ma	em. Note: i anufacture	if the item is an as r has engineering	sembly with lowe responsibility.
1752-21.1	21.1 IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
Supplie	r Information														
Company name* Company unique ID					1	Unique ID Authority Response Date*									
onsemi											2025-06-03				
Contact N	lame		Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-l	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorize	ed Representative*	Title - Representative			1	Phone - Representative*			Email - Representative*						
Product-1	Env-Stewards		Product Envi	ro Compliance	Compliance NA Product-Env-Stewards@onsemi.co					m					
	Requester Item Number Mfr Item		Number Mfr Item Name			Effective Da	ite Ver	sion	Manufacturing Site		V	Veight*	UOM	Unit Type	
		STK5311	U369A-E	Inverter			2025-06-03			VN2		1	4100.0	mg	Each
Manufa	cturing Proccess Informat	tion		•				•						•	
	Terminal Plating / Grid Array Material T		erminal Base	Alloy	J-STD-020 MSL Ra		Peak Pr	ocess Bo	dy Temperatu	ature Max Time at Peak		Temperatu	re Numb	per of Reflow Cyc	les
	Matte Tin (Sn) - annealed	C	CU Alloy		NA		0		C	30		second	ls 3		
Comments	3			·							·				·
or more	information regarding material	composition	please refer to	page 3		· · · · · · · · · · · · · · · · · · ·									

RoHS Material Composition Declaration			Declaration 7	Гуре *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its uppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier neter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Suppli											
RoHS Declaration * 4 - Item(s	does not contain RoHS restricted substances	per the definition above except for sele	ted exemptions	Supplier Acceptance	* Accepted						
Exemption: 7c-I Electrical and electronic co	omponents containing lead in a glass or cera	mic other than dielectric ceramic in	apacitors, e.g. piezoelect	ronic devices, or in a glass or co	eramic matrix compound.						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		ccepted" on the Supplier Acceptance	drop-down. This will dis	play the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	astislav Drska	E_									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	3930.48	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		49.131	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		193.7727	mg
			В	Nickel (Ni)	7440-02-0		6.6818	mg
			Supplier	Acrylic resins	Proprietary Data		2.7513	mg
			Supplier	Copper (Cu)	7440-50-8		264.1282	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		1.9652	mg
			Supplier	Aluminum (Al)	7429-90-5		3412.0496	mg
Chip Parts	45.36	mg	Supplier	Silver (Ag)	7440-22-4		1.2338	mg
			Supplier	Epoxy resins	129915-35-1		0.4355	mg
			Supplier	Tin (Sn)	7440-31-5		1.3427	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		0.0635	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.7802	mg
			Supplier	Ceramic	12013-47-7, 12047- 27-7		8.4642	mg
			Supplier	Phenolic resins	Proprietary Data		0.0544	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0045	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		27.7104	mg
			В	Nickel (Ni)	7440-02-0		2.2272	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.0635	mg
			Supplier	Copper (Cu)	7440-50-8		2.6762	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.3039	mg
Die	30.06	mg	Supplier	Silicon (Si)	7440-21-3		30.06	mg
Die Attach	1.62	mg	Supplier	Silver (Ag)	7440-22-4		1.1034	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.2435	mg
			Supplier	Tin (Sn)	7440-31-5		0.1714	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0616	mg
			В	Antimony (Sb)	7440-36-0		0.0159	mg
			В	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0243	mg
Heat Sink	869.5	mg	Supplier	Silver (Ag)	7440-22-4		139.12	mg
			Supplier	Copper (Cu)	7440-50-8		730.38	mg
Lead Frame	527.07	mg	Supplier	Tin (Sn)	7440-31-5		0.3162	mg
			Supplier	Copper (Cu)	7440-50-8		526.7538	mg

Mold Compound-Black	8586.38	mg		Brominated epoxy resin	proprietary data	18.89	mg
			Supplier	Phenolic Resin	Proprietary Data	443.0572	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4	13.7382	mg
			Supplier	Carbon Black (C)	1333-86-4	35.2042	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2	609.633	mg
			Supplier	Fused Silica (SiO2)	60676-86-0	5712.5186	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2	944.5018	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7	808.837	mg
Plating	1.05	mg	Supplier	Tin (Sn)	7440-31-5	0.6501	mg
			В	Nickel (Ni)	7440-02-0	0.3999	mg
Solder Ball	19.87	mg	Supplier	Silver (Ag)	7440-22-4	0.5544	mg
			Supplier	Tin (Sn)	7440-31-5	19.2024	mg
			В	Antimony (Sb)	7440-36-0	0.0159	mg
			Supplier	Copper (Cu)	7440-50-8	0.0974	mg
Wire Bond - Al	88.61	mg	Supplier	Aluminum (Al)	7429-90-5	88.61	mg